## The Most **Reliable** Storage For Industries

## PT160-M280





## PT160-M280

### Overview

Apacer PT160-M280 is the fastest SSD designed as M.2 2280 mechanical dimensions which provides full compliance with PCIe Gen4 x4 interface and NVMe 1.4 specifications, allowing it to operate in power management modes and greatly save on power consumption. Built with a powerful PCIe controller that supports on-the-module ECC as well as efficient wear leveling scheme, PT160-M280 delivers exceptionally low latency and outstanding performance in data transfer, reaching up to 909,000/517,000 and 6,970/2,310 MB/s in IOPS and sequential read/write. With the compact and high-speed storage, PT160-M280 is the ideal choice for larger, faster hosts deployed in a wide range of applications that require outstanding performance.





Utilizing 3D NAND for higher capacity up to 8TB and providing more power efficiency than 2D NAND, PT160-M280 is not only implemented with LDPC (Low Density Parity Check) ECC engine to extend SSD endurance and increase data reliability, but also equipped with a built-in thermal sensor to monitor the temperature of the SSD via S.M.A.R.T commands and configured with thermal throttling to dynamically adjust frequency scaling to enhance data reliability and provide sustained performance while overheating. To ensure that products continue to operate normally in high vibration and under extreme environmental changes, Apacer provides Sidefill technology to increase product reliability and resistance to various thermal and mechanical shocks as well as a graphene heat spreader to help keep an SSD cool and functioning correctly. For highly-intensive applications, End-to-End Data Protection ensures that data integrity can be assured at multiple points in the path to enable reliable delivery of data transfers.

In terms of security, Advanced Encryption Standard (AES) ensures data security and provides users with peace of mind knowing their data is safeguarded against unauthorized use at all times. PT160-M280 also adopts the latest page mapping file translation layer and comes with various implementations including power saving modes, wear leveling, flash block management, power failure management, TRIM, SMART Read Refresh, and NVMe secure erase. With exceptional performance, trustable reliability, and enhanced data protection, PT160-M280 is definitely the ideal storage or cache solution for a variety of applications ranging from industrial, imaging, computing to enterprise markets.

### **Feature**

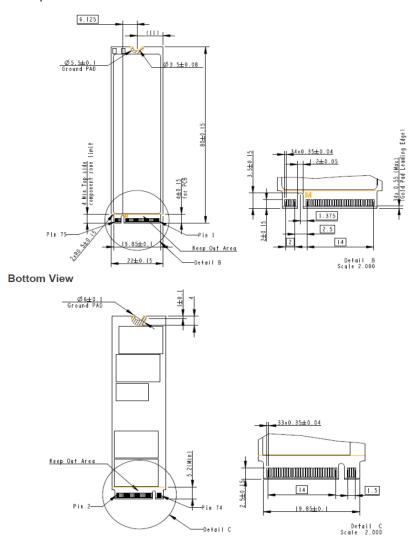
- Supports large capacity of up to 8TB (standard) and 4TB (wide-temp)
- Adopts advanced LDPC ECC engine with 3D NAND flash memory to improve reliability
- Global Wear Leveling
- Flash bad-block management
- Flash Translation Layer: Page Mapping
- Supports SSDWidget S.M.A.R.T function
- Heat spreader technology
- Power Failure Management
- AES 256-bit hardware encryption
- End-to-End Data Protection
- TRIM Support
- Over-provisioning
- SMART Read Refresh™
- NVMe Secure Erase

## Specifications

Model     PT160-M280       Interface     PCIe Gen4 x4       Connector     Double-sided M.2 2280-M       Form Factor     M.2 2280       NAND Flash Type     3D TLC       Capacity     4TB ~ 8TB       External DRAM     Yes       Sequential Read Performance (MB/sec)     Up to 6970       Sequential Write Performance (MB/sec)     Up to 2310       ECC Engine     Low-Density Parity-Check (LDPC) Code       IOPs (4K Random Write)     517K       Standard Operating Temperature (°C)     -40 ~ +85 (8TB not support)       Temperature (°C)     -55 ~ +100       Storage Temperature (°C)     -55 ~ +100       Thermal sensor     Yes       Operating: Acceleration, 50(G)/11(ms)/half sine (compliant with MIL-STD-202G) Non-operation; Acceleration, 1500(G)/0.5(ms)/half sine (compliant with MIL-STD-810G)       Vibration     Operation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G)       Vibration Vibration     Non-operation: 4.02 Grms, 15~2000 Hz/random (compliant with MIL-STD-810G)       Operating Voltage     3.3V ± 5%       Power Consumption     Active mode: 3750 mA / Idle mode: 900 mA       Dimension (L x W x H)     22.00 x 80.00 x 4.08 (max.) (mm)       MTBF (hours)     >3,000,000		
Connector     Double-sided M.2 2280-M       Form Factor     M.2 2280       NAND Flash Type     3D TLC       Capacity     4TB ~ 8TB       External DRAM     Yes       Sequential Read Performance (MB/sec)     Up to 6970       Sequential Write Performance (MB/sec)     Up to 2310       ECC Engine     Low-Density Parity-Check (LDPC) Code       IOPs (4K Random Write)     517K       Standard Operating Temperature (°C)     -40 ~ +85 (8TB not support)       Extended Operating Temperature (°C)     -55 ~ +100       Storage Temperature (°C)     Operating: Acceleration, 50(g)/11(ms)/half sine (compliant with MIL-STD-202G) Non-operating: Acceleration, 1500(G)/0.5(ms)/half sine (compliant with MIL-STD-883K)       Vibration     Operation:7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G) Non-operation:4.02 Grms, 15~2000 Hz/random (compliant with MIL-STD-810G)       Operating Voltage     3.3V ± 5%       Power Consumption     Active mode: 3750 mA / Idle mode:900 mA       Dimension (L x W x H)     22.00 x 80.00 x 4.08 (max.) (mm)	Model	PT160-M280
Form Factor  NAND Flash Type  3D TLC  Capacity  4TB ~ 8TB  External DRAM  Yes  Sequential Read Performance (MB/sec)  Sequential Write Performance (MB/sec)  ECC Engine  Low-Density Parity-Check (LDPC) Code  IOPs (4K Random Write)  Standard Operating Temperature (°C)  Extended Operating Temperature (°C)  Storage Temperature (°C)  Thermal sensor  Shock  Operating: Acceleration, 50(g)/11(ms)/half sine (compliant with MIL-STD-202G) Non-operating: Acceleration, 1500(G)/0.5(ms)/half sine (compliant with MIL-STD-883K)  Vibration  Operating: Operating: Acceleration, 50(G)/ms, 15~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 4.02 Grms, 15~2000 Hz/random (compliant with MIL-STD-810G) Operating Voltage  Operating Voltage  Operating Voltage  Operating Voltage  Active mode: 3750 mA / Idle mode:900 mA  Dimension (L x W x H)  22.00 x 80.00 x 4.08 (max.) (mm)	Interface	PCIe Gen4 x4
NAND Flash Type  Capacity  Capacity  External DRAM  Sequential Read Performance (MB/sec)  Sequential Write Performance (MB/sec)  CC Engine  Low-Density Parity-Check (LDPC) Code  IOPs (4K Random Write)  Standard Operating Temperature (°C)  Extended Operating Temperature (°C)  Storage Temperature (°C)  Thermal sensor  Operating: Acceleration, 50(G)/11(ms)/half sine (compliant with MIL-STD-202G) Non-operating: Acceleration, 1500(G)/0.5(ms)/half sine (compliant with MIL-STD-883K)  Vibration  Operating: Acceleration, 200 (G)/0.5(ms)/half sine (compliant with MIL-STD-883K)  Operation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 4.02 Grms, 15~2000 Hz/random (compliant with MIL-STD-810G)  Operating Voltage  3.3V ± 5%  Power Consumption  Active mode: 3750 mA / Idle mode: 900 mA  Dimension (L x W x H)  22.00 x 80.00 x 4.08 (max.) (mm)	Connector	Double-sided M.2 2280-M
Capacity External DRAM  Sequential Read Performance (MB/sec)  Sequential Write Performance (MB/sec)  CC Engine  Low-Density Parity-Check (LDPC) Code  IOPs (4K Random Write)  Standard Operating Temperature (°C)  Extended Operating Temperature (°C)  Storage Temperature (°C)  Thermal sensor  Shock  Operating: Acceleration, 50(G)/11(ms)/half sine (compliant with MIL-STD-202G) Non-operating: Acceleration, 1500(G)/0.5(ms)/half sine (compliant with MIL-STD-883K)  Operating: Acceleration, 1500(G)/0.5(ms)/half sine (compliant with MIL-STD-883K)  Operating: Acceleration, 1500(G)/0.5(ms)/half sine (compliant with MIL-STD-883K)  Operating: Acceleration, 1500(G)/0.5(ms)/half sine (compliant with MIL-STD-810G) Non-operating: Acceleration, 1500(G)/0.5(ms)/half sine (compliant with MIL-STD-810G)  Non-operation: 4.02 Grms, 15~2000 Hz/random (compliant with MIL-STD-810G)  Operating Voltage  3.3V ± 5%  Power Consumption  Active mode: 3750 mA / Idle mode: 900 mA  Dimension (L x W x H)  22.00 x 80.00 x 4.08 (max.) (mm)	Form Factor	M.2 2280
External DRAM       Yes         Sequential Read Performance (MB/sec)       Up to 6970         Sequential Write Performance (MB/sec)       Up to 2310         ECC Engine       Low-Density Parity-Check (LDPC) Code         IOPs (4K Random Write)       517K         Standard Operating Temperature (°C)       0 ~ +70         Extended Operating Temperature (°C)       -40 ~ +85 (8TB not support)         Storage Temperature (°C)       -55 ~ +100         Thermal sensor       Yes         Operating: Acceleration, 50(G)/11(ms)/half sine (compliant with MIL-STD-202G) Non-operating: Acceleration, 1500(G)/0.5(ms)/half sine (compliant with MIL-STD-83K)         Vibration       Operation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 4.02 Grms, 15~2000 Hz/random (compliant with MIL-STD-810G)         Operating Voltage       3.3V ± 5%         Power Consumption       Active mode: 3750 mA / Idle mode: 900 mA         Dimension (L x W x H)       22.00 x 80.00 x 4.08 (max.) (mm)	NAND Flash Type	3D TLC
Sequential Read Performance (MB/sec)  Sequential Write Performance (MB/sec)  ECC Engine  Low-Density Parity-Check (LDPC) Code  IOPs (4K Random Write)  Standard Operating Temperature (°C)  Extended Operating Temperature (°C)  Storage Temperature (°C)  Thermal sensor  Operating: Acceleration, 50(G)/11(ms)/half sine (compliant with MIL-STD-202G) Non-operating: Acceleration, 1500(G)/0.5(ms)/half sine (compliant with MIL-STD-883K)  Vibration  Operating: Acceleration, 50 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 4.02 Grms, 15~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 4.02 Grms, 15~2000 Hz/random (compliant with MIL-STD-810G) Active mode: 3750 mA / Idle mode: 900 mA  Dimension (L x W x H)  22.00 x 80.00 x 4.08 (max.) (mm)	Capacity	4TB ~ 8TB
Sequential Write Performance (MB/sec)  ECC Engine  Low-Density Parity-Check (LDPC) Code  IOPS (4K Random Write)  Standard Operating Temperature (°C)  Extended Operating Temperature (°C)  Storage Temperature (°C)  Thermal sensor  Shock  Operating: Acceleration, 50(G)/11(ms)/half sine (compliant with MIL-STD-202G) Non-operating: Acceleration, 1500(G)/0.5(ms)/half sine (compliant with MIL-STD-83K)  Operation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 4.02 Grms, 15~2000 Hz/random (compliant with MIL-STD-810G) Operating Voltage  3.3V ± 5% Power Consumption  Active mode: 3750 mA / Idle mode: 900 mA  Dimension (L x W x H)  22.00 x 80.00 x 4.08 (max.) (mm)	External DRAM	Yes
COMB/sec   Compliant with MIL-STD-883K	-	Up to 6970
IOPs (4K Random Write)  Standard Operating Temperature ( °C )  Extended Operating Temperature ( °C )  Storage Temperature ( °C )  Thermal sensor  Shock  Operating: Acceleration, 50(G)/11(ms)/half sine (compliant with MIL-STD-202G) Non-operating: Acceleration, 1500(G)/0.5(ms)/half sine (compliant with MIL-STD-883K)  Operation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 4.02 Grms, 15~2000 Hz/random (compliant with MIL-STD-810G)  Operating Voltage  Power Consumption  Active mode: 3750 mA / Idle mode: 900 mA  Dimension (L x W x H)  22.00 x 80.00 x 4.08 (max.) (mm)	-	Up to 2310
Standard Operating Temperature ( °C )  Extended Operating Temperature ( °C )  Storage Temperature ( °C )  Thermal sensor  Operating: Acceleration, 50(G)/11(ms)/half sine (compliant with MIL-STD-202G) Non-operating: Acceleration, 1500(G)/0.5(ms)/half sine (compliant with MIL-STD-883K)  Vibration  Operation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 4.02 Grms, 15~2000 Hz/random (compliant with MIL-STD-810G)  Operating Voltage  3.3V ± 5%  Power Consumption  Active mode: 3750 mA / Idle mode: 900 mA  Dimension (L x W x H)  22.00 x 80.00 x 4.08 (max.) (mm)	ECC Engine	Low-Density Parity-Check (LDPC) Code
Temperature (°C)  Extended Operating Temperature (°C)  Storage Temperature (°C)  Thermal sensor  Shock  Operating: Acceleration, 50(G)/11(ms)/half sine (compliant with MIL-STD-202G) Non-operating: Acceleration, 1500(G)/0.5(ms)/half sine (compliant with MIL-STD-883K)  Operation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 4.02 Grms, 15~2000 Hz/random (compliant with MIL-STD-810G)  Operating Voltage  Power Consumption  Active mode: 3750 mA / Idle mode: 900 mA  Dimension (L x W x H)  22.00 x 80.00 x 4.08 (max.) (mm)	IOPs (4K Random Write)	517K
Temperature (°C)  Storage Temperature (°C)  Thermal sensor  Operating: Acceleration, 50(G)/11(ms)/half sine (compliant with MIL-STD-202G) Non-operating: Acceleration, 1500(G)/0.5(ms)/half sine (compliant with MIL-STD-883K)  Operation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 4.02 Grms, 15~2000 Hz/random (compliant with MIL-STD-810G)  Operating Voltage  3.3V ± 5%  Power Consumption  Active mode: 3750 mA / Idle mode: 900 mA  Dimension (L x W x H)  22.00 x 80.00 x 4.08 (max.) (mm)		0~+70
Thermal sensor  Operating: Acceleration, 50(G)/11(ms)/half sine (compliant with MIL-STD-202G) Non-operating: Acceleration, 1500(G)/0.5(ms)/half sine (compliant with MIL-STD-883K)  Operation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 4.02 Grms, 15~2000 Hz/random (compliant with MIL-STD-810G)  Operating Voltage  3.3V ± 5%  Power Consumption  Active mode: 3750 mA / Idle mode: 900 mA  Dimension (L x W x H)  22.00 x 80.00 x 4.08 (max.) (mm)		-40 ~ +85 (8TB not support)
Shock  Operating: Acceleration, 50(G)/11(ms)/half sine (compliant with MIL-STD-202G) Non-operating: Acceleration, 1500(G)/0.5(ms)/half sine (compliant with MIL-STD-883K)  Operation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 4.02 Grms, 15~2000 Hz/random (compliant with MIL-STD-810G)  Operating Voltage  3.3V ± 5%  Power Consumption  Active mode: 3750 mA / Idle mode: 900 mA  Dimension (L x W x H)  22.00 x 80.00 x 4.08 (max.) (mm)	Storage Temperature ( °C )	-55 ~ +100
(compliant with MIL-STD-202G) Non-operating: Acceleration, 1500(G)/0.5(ms)/half sine (compliant with MIL-STD-883K)  Operation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 4.02 Grms, 15~2000 Hz/random (compliant with MIL-STD-810G)  Operating Voltage  3.3V ± 5%  Power Consumption Active mode: 3750 mA / Idle mode: 900 mA  Dimension (L x W x H)  22.00 x 80.00 x 4.08 (max.) (mm)	Thermal sensor	Yes
Vibration(compliant with MIL-STD-810G) Non-operation:4.02 Grms, 15~2000 Hz/random (compliant with MIL-STD-810G)Operating Voltage3.3V ± 5%Power ConsumptionActive mode: 3750 mA / Idle mode:900 mADimension (L x W x H)22.00 x 80.00 x 4.08 (max.) (mm)	Shock	(compliant with MIL-STD-202G) Non-operating: Acceleration, 1500(G)/0.5(ms)/half sine
Power Consumption  Active mode: 3750 mA / Idle mode:900 mA  Dimension (L x W x H)  22.00 x 80.00 x 4.08 (max.) (mm)	Vibration	(compliant with MIL-STD-810G) Non-operation:4.02 Grms, 15~2000 Hz/random
Dimension (L x W x H ) 22.00 x 80.00 x 4.08 (max.) (mm)	Operating Voltage	3.3V ± 5%
	Power Consumption	Active mode: 3750 mA / Idle mode:900 mA
MTBF (hours) >3,000,000	Dimension (L x W x H )	22.00 x 80.00 x 4.08 (max.) (mm)
	MTBF (hours)	>3,000,000

### **Mechanical Specification**

#### **Top View**



Unit: mm

# For more information, contact your Apacer representative

### Global Presence

Taiwan (Headquarters) Apacer Technology Inc. Tel: +886-2-2267-8000 Fax: +886-2-2267-2261

Apacer Technology B.V. Tel: +31-40-267-0000 Fax: +31-40-290-0686 U.S.A. Apacer Memory America, Inc. Tel: +1-408-518-8699 Fax: 1-510-249-9551 Shanghai Apacer Electronic(Shanghai) Co., Ltd. Tel: +86-21-6228-9939

Japan

Apacer Technology Corp.
Tel: +81-3-5419-2668
Fax: +81-3-5419-0018

Apacer Technologies Pvt. Ltd. Tel: +91-80-41529061~3 Fax: +91-80-41700215